

Title (en)  
TWO-COMPONENT CURING COMPOSITION FOR METAL SURFACE TREATMENT, METHOD FOR MOUNTING FILM ON METAL SURFACE, AND SURFACE STRUCTURE

Title (de)  
ZWEIKOMPONENTIGE HÄRTUNGSZUSAMMENSETZUNG ZUR METALLOBERFLÄCHENBEHANDLUNG, VERFAHREN ZUR MONTAGE EINES FILMS AUF EINER METALLOBERFLÄCHE UND OBERFLÄCHENSTRUKTUR

Title (fr)  
COMPOSITION DE DURCISSEMENT À DEUX COMPOSANTS POUR LE TRAITEMENT D'UNE SURFACE MÉTALLIQUE, PROCÉDÉ D'APPLICATION D'UN FILM SUR UNE SURFACE MÉTALLIQUE ET STRUCTURE DE SURFACE

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Application  
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Abstract (en)  
[origin: WO2021250595A1] A two-component curing composition for metal surface treatment, a method for mounting a film on a metal surface, and a surface structure are provided in the present invention. The two-component curing composition comprises: 15-35 wt% of a liquid epoxy resin; 20-35 wt% of a curing agent for epoxy resin; 5-15 wt% of a diluent; 10-25 wt% of a weight reducing agent; and 5-20 wt% of a flame retardant; wherein the two-component curing composition comprises a part A and a part B, the part A comprising the liquid epoxy resin, the part B comprising the curing agent for epoxy resin, and the diluent, the weight reducing agent and the flame retardant are present in one or both of the part A and the part B. The two-component curing composition for metal surface treatment has good open time and surface drying time when applied, and has a very high bonding strength to the metal surface to be treated and aging resistance. By means of the use of the composition, convenient, simple, and quick mounting of a film on the metal surface (e.g., a surface of a vehicle body) can be realized.

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Cited by  
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